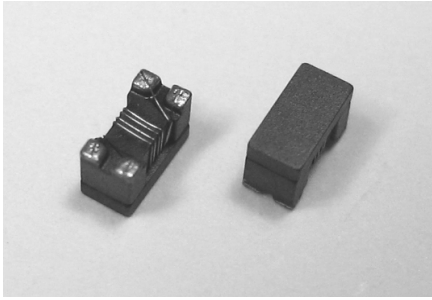


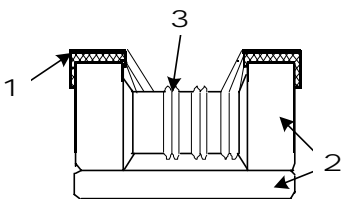
SLF4532 Series (Size: 4532(1812))



■ Features

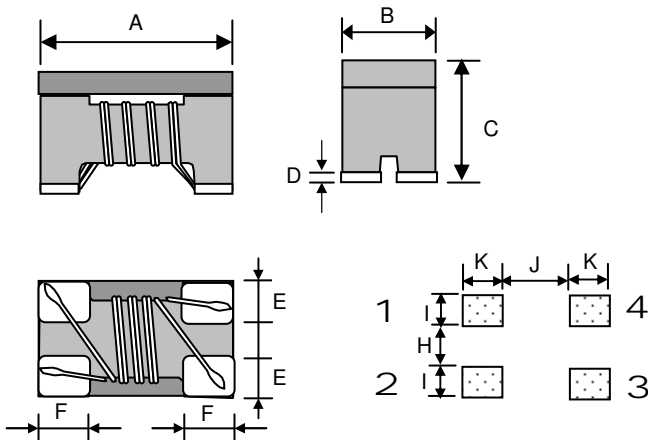
- Small chip inductor with ferrite core and two line types wire wound
- Highly effective in noise suppression High common-mode impedance at noise band and low differential-mode impedance at signal band
- Low differential-mode impedance with high coupling factor. There is almost no distortion on high-speed signal.
- Operating temperature -20 °C~85 °C

■ Construction

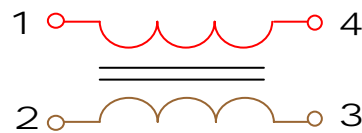


1	Terminal	2	Ferrite	3	Enamel-insulated Wire
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■ Dimensions



■ Equivalent Circuit

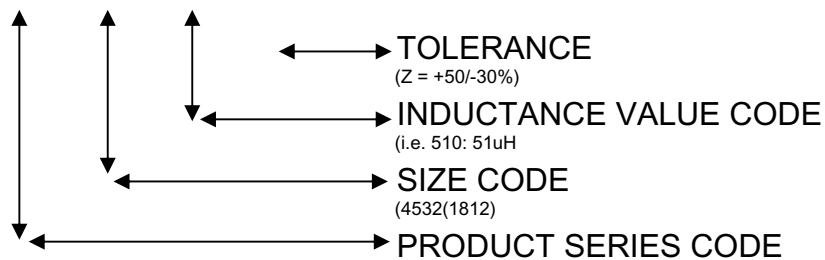


Unit : mm

Type	Size (Inch)	A	B	C	D	E	F	H	I	J	K
SLF4532	1812	4.5±0.2	3.2±0.2	2.8±0.2	0.2±0.1	1.2	1.0	0.75	1.2	2.4	1.0

■ Part Numbering

SLF 4532-510 Z



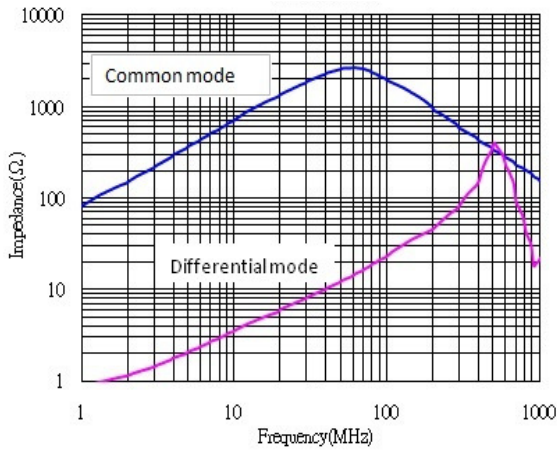
SLF4532 Series (Size: 4532(1812))

Standard Electrical Specifications

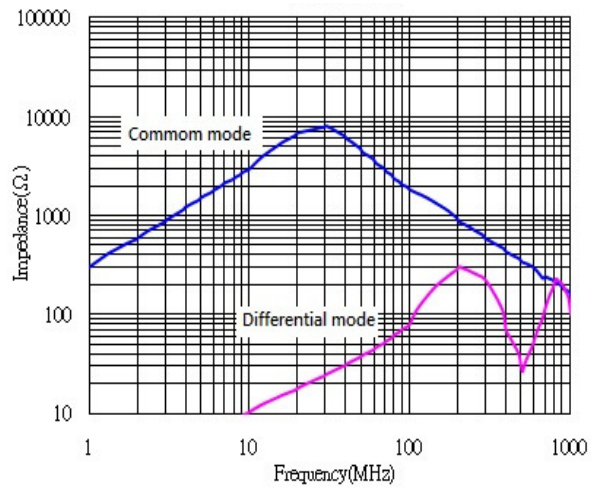
Part No.	Impedance(Ω) @10MHz		Inductance(μ H) @100KHz	Inductance Tolerance	DCR (Ω) max.	IDC (mA) max.	Rated Voltage Vdc (V) typ.	Insulation Resistance ($M\Omega$) min.
	min.	typ.						
SLF4532-110Z	300	700	11	+50/-30%	0.60	250	50	10
SLF4532-220Z	500	1000	22	+50/-30%	1.00	200	50	10
SLF4532-510Z	1000	2000	51	+50/-30%	1.00	200	50	10
SLF4532-101Z	2000	5000	100	+50/-30%	3.00	150	50	10

Characteristics (Impedance vs. Frequency)

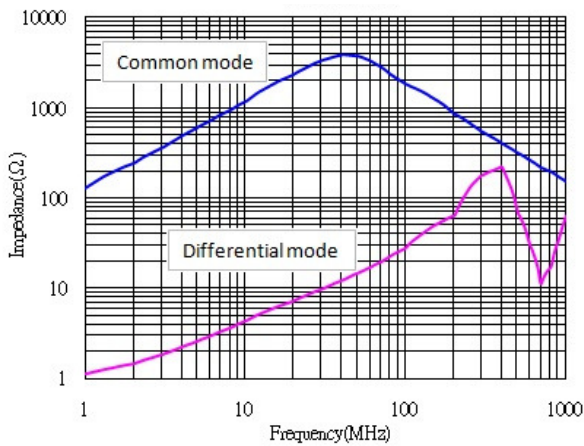
SLF4532-110Z



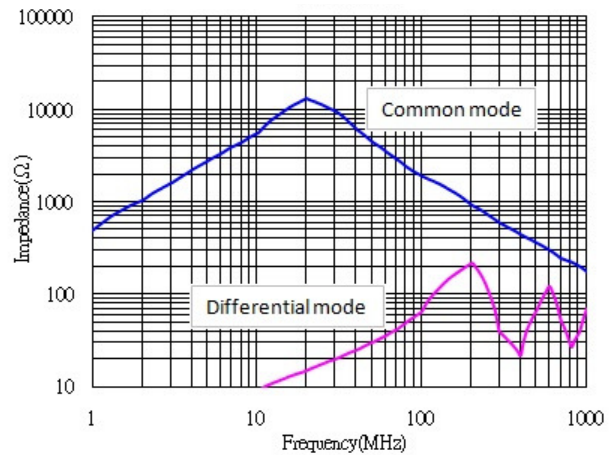
SLF4532-220Z



SLF4532-510Z



SLF4532-101Z



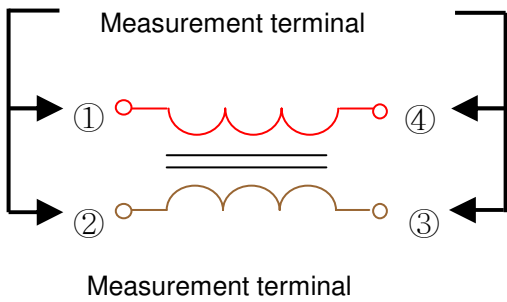
SLF4532 Series (Size: 4532(1812))

Test Equipment

Impedance/Inductance

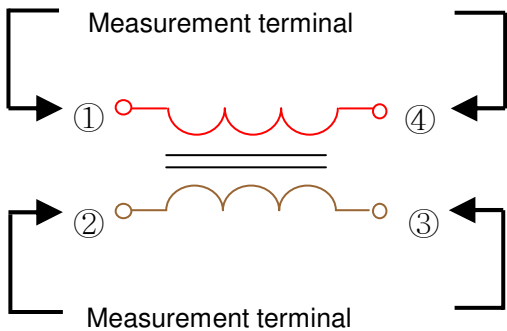
Measured by using Agilent 4291A RF Impedance Analyzer.

Measured by using Microtest 6377 LCR meter.



DC Resistance

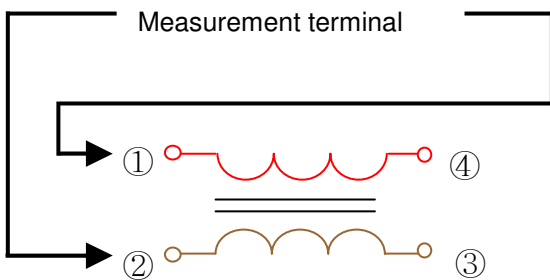
Measured by using Chroma 16502 mill ohm meter.



Insulation Resistance

Measured by using Chroma 19073

Measurement voltage : 50v ,Measurement time : 60 sec



SLF4532 Series (Size: 4532(1812))

Environmental Characteristics

Mechanical Performance Test

Items	Requirement	Test Conditions / Test Methods
Solderability	The terminal should at least be 90% covered with solder	The component shall be dipped in a melted solder bath at 245 ±5°C for 3 seconds
Solder Heat Resistance	Impedance change: Within± 15% Without distinct damage in appearance	Preheating: 150°C for 60secs Solder temperature: 260±5°C for 10 seconds
Terminal Strength	Force :1.0 Kg	Solder a chip to test substrate and then laterally apply a force in the arrow direction

Climatic Test

Items	Requirement	Test Conditions / Test Methods
Low Temperature Storage	Impedance change: Within± 15% Without distinct damage in appearance	1. Temp: -25 ±2°C 2. Time: 168±5 Hours 3. Component should be tested after 1 hour at room temperature
Thermal Shock		-25°C, (30mins)→room temp. (5mins)→ 125°C, (30mins)→room temp. (5mins) Total: 10 Cycles
High Temperature Storage		1. Temp: 125 ± 2°C 2. Time: 168 ± 5 Hours 3. Component should be tested after 1 hour at room temperature
Humidity Resistance		1. Apply IDC current @60°C ambient 2. R.H. : 80% 3. Time: 168 Hours